J.A.M.E.S

SIP – System in Package

Story

Requirements
and targeted architecture

SIP – System in Package

Introduction of your requirement and architecture content:

1. Architecture
PCS – Printed Circuit Structures
SIP design

2. Requirements
Mechanical requirements:
1. Flat top and bottom surfaces to enable connection.
2. Low vibrations withstand.
3. Limited dimensions of 11X11X1.5 mm.
4. Mechanical connection to motherboard.
5. Working temperature up to 120^0C.
6. Withstand falling from 2 meters height.
7. Using dies placing in the design.

Electrical requirements:
1. 4W output
2. 50-Ohm main line.
3. Shielding for the main line.
4. Contain AME structures for passive components.
5. Main frequencies 10MHz
6. Supported frequencies 1-100MHz.

Overall requirements:
1. Fully automatic process